

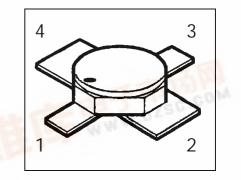


BFY193

HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain amplifiers up to 2GHz.
- For linear broadband amplifiers
- Hermetically sealed microwave package
- f_T= 8 GHz
 F = 2.3 dB at 2 GHz
- **CC CSA** Space Qualified ESA/SCC Detail Spec. No.: 5611/006 Type Variant No. 06

ESD: Electrostatic discharge sensitive device, observe handling precautions!



Туре	Marking	Ordering Code	Pin (Config	guratio	on	Package
	EL DIS		1	2	3 4	ļ	
BFY193 (ql)	N WWW	see below	С	E	В	E	Micro-X1

(ql) Quality Level:

- P: Professional Quality,
- H: High Rel Quality,
- S: Space Quality,
- ES: ESA Space Quality,

Ordering Code:	Q62702F1610
Ordering Code:	on request
Ordering Code:	on request
Ordering Code:	Q62702F1701

(see order instructions for ordering example)





Maximum Ratings

Parameter	Symbol	Values	Unit	
Collector-emitter voltage	V _{CEO}	12	V	
Collector-emitter voltage, $V_{BE}=0$	V _{CES}	20	V	
Collector-base voltage	V _{CBO}	20	V	
Emitter-base voltage	V _{EBO}	2	V	
Collector current	Ι _C	80	mA	
Base current	Ι _Β	10 ¹⁾	mA	
Total power dissipation, $T_S \leq 104^{\circ}C^{-2), 3)}$	P _{tot}	580	mW	
Junction temperature	Tj	200	°C	
Operating temperature range	T _{op}	-65+200	°C	
Storage temperature range	T _{stg}	-65+200	°C	

Thermal Resistance

Junction-soldering point ³⁾	e _{th JS} < 165	K/W
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Notes .:

1) The maximum permissible base current for V_{FBE} measurements is 30mA (spot-measurement duration < 1s)

2) At T_S = + 104 °C. For T_S > + 104 °C derating is required.

3) T_s is measured on the collector lead at the soldering point to the pcb.

Electrical Characteristics

at $T_A=25^{\circ}C$; unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	

DC Characteristics

Collector-base cutoff current	I _{CBO}	-	-	100	μA
$V_{CB} = 20 V$, $I_E = 0$					
Collector-emitter cutoff current	I _{CEX}	-	-	600	μA
$V_{CE} = 12 V$, $I_B = 0.5 \mu A^{-1.3}$					
Collector-base cutoff current	I _{CBO}	-	-	50	nA
$V_{CB} = 10 V, I_{E} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	25	μA
$V_{EB} = 2 V, I_{C} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μA
$V_{EB} = 1 V, I_{C} = 0$					

Notes:

1.) This Test assures V(BR)CE0 > 12V



Electrical Characteristics (continued)

Parameter	Symbol		Values	5	Unit
		min.	typ.	max.	
DC Characteristics					
Base-Emitter forward voltage	V_{FBE}	-	-	1	V
$I_{E} = 30 \text{ mA}, I_{C} = 0$					
DC current gain	h _{FE}	50	100	175	-
$I_{C} = 30 \text{ mA}, V_{CE} = 8 \text{ V}$					
AC Characteristics					
Transition frequency	f _T				GHz
$I_{\rm C}$ = 40mA, $V_{\rm CE}$ = 5 V, f = 500 MHz		6,5	7.5	-	
$I_{\rm C}$ = 50 mA, $V_{\rm CE}$ = 8 V, f = 500 MHz		-	8	-	
Collector-base capacitance	C _{CB}	-	0.56	0.75	pF
V_{CB} = 10 V, V_{BE} = vbe = 0, f = 1 MHz					
Collector-emitter capacitance	C _{CE}	-	0.34	-	pF
V_{CE} = 10 V, V_{BE} = vbe = 0, f = 1 MHz					
Emitter-base capacitance	C _{EB}	-	1.9	2.4	pF
V_{EB} = 0.5V, V_{CB} = vcb = 0, f = 1 MHz					
Noise Figure	F	-	2.3	2.9	dB
I_{C} = 15 mA, V_{CE} = 5 V, f = 2 GHz,					
$Z_S = Z_{Sopt}$					
Power gain	Gma ^{1.)}	12.5	13.5	-	dB
I_{C} = 40 mA, V_{CE} = 5V, f = 2 GHz					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
Transducer gain	$ S_{21e} ^2$	8	9	-	dB
I_{C} = 40 mA, V_{CE} = 5 V, f = 2 GHz					
$Z_S = Z_L = 50 \ \Omega$					
Output Power	P _{OUT}	16.5	17.5	-	dBm
I_{C} = 50 mA, V_{CE} = 5 V, f = 2GHz,					
P_{IN} =10dBm, Z_{S} = Z_{L} = 50 Ω					

Notes .:

1.)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q..... BFY193 (ql) (ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1701 BFY193 ES For BFY193 in ESA Space Quality Level

Further Informations:

See our WWW-Pages:

- Discrete and RF-Semiconductors (Small Signal Semiconductors) www.infineon.com/product/discrete/hirel.htm
- *HiRel* Discrete and Microwave Semiconductors www.infineon.com/product/discrete/hirel.htm

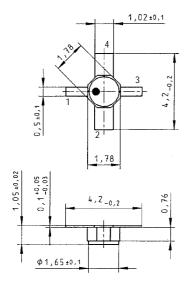
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Micro-X1 Package



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